	L #	Hits	Search Text	DBs
1	L1	525	361/720.ccls.	US-PGPUB; USPAT
2	L2	0	1 and ((core with ((dissipat$3 thermal$2) adj layer$1)) with (coefficient$1 expansion cte tce tec))	US-PGPUB; USPAT
3	L3	0	1 and (core with ((dissipat$3 thermal$2) adj layer$1)) with (coefficient$1 expansion cte tce tec)	US-PGPUB; USPAT
4	L4	8	1 and (core with (coefficient$1 expansion cte tce tec))	US-PGPUB; USPAT
5	L5	105	1 and ((dissipation cooling) and (coefficient$1 expansion cte tce tec))	US-PGPUB; USPAT
6	L6	100	5 not 4	US-PGPUB; USPAT
7	L7	1161	361/719.ccls.	US-PGPUB; USPAT
8	L8	0	7 and (core with ((dissipat$3 thermal$2) adj layer$1)) with (coefficient$1 expansion cte tce tec)	US-PGPUB; USPAT

	L #	Hits	Search Text	DBs
9	L9	7	7 and (core with (coefficient$1 expansion cte tce tec))	US-PGPUB; USPAT
10	L10	431	(361/780,794.ccls.)	US-PGPUB; USPAT
11	L11	72	10 and (multi$1chip mcm "plurality of (chip$1 semiconductor$1 die$1)")	US-PGPUB; USPAT
12	L12	1684	257/723.ccls.	US-PGPUB; USPAT
13	L13	0	12 and (("interconnected with each other") ("interconnected with one another"))	US-PGPUB; USPAT
14	L14	487	12 and (multi$1layer$2 multi$1level)	US-PGPUB; USPAT
15	L15	219	14 and (multi$1chip mcm "plurality of (chip$1 semiconductor$1 die)")	US-PGPUB; USPAT
16	L16	0	wo-02061827-$.did.	DERWENT